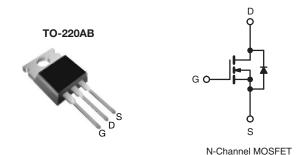


Power MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	50	500				
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V 1.5					
Q _g (Max.) (nC)	38					
Q _{gs} (nC)	5.0					
Q _{gd} (nC)	22					
Configuration	Single					



FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Fast Switching
- · Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC





DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF830PbF		
	SiHF830-E3		
SnPb	IRF830		
SIIFD	SiHF830		

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise parameter			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	500		
Gate-Source Voltage			V _{GS}	± 20	V	
Continuous Dusin Comment	V -+ 10 V	T _C = 25 °C		4.5	А	
Continuous Drain Current	V _{GS} at 10 V	$T_C = 25 \degree C$ $T_C = 100 \degree C$	I _D	2.9		
Pulsed Drain Current ^a		I _{DM}	18			
Linear Derating Factor				0.59	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	280	mJ	
Repetitive Avalanche Current ^a			I _{AR}	4.5	А	
Repetitive Avalanche Energy ^a			E _{AR}	7.4	mJ	
Maximum Power Dissipation $T_C = 25 ^{\circ}C$			P _D	74	W	
Peak Diode Recovery dV/dt ^c			dV/dt	3.5	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature) for 10 s				300 ^d		
Mounting Torque	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. $V_{DD} = 50 \text{ V}$, starting $T_J = 25 \,^{\circ}\text{C}$, $L = 24 \,\text{mH}$, $R_g = 25 \,\Omega$, $I_{AS} = 4.5 \,\text{A}$ (see fig. 12).
- c. $I_{SD} \le 4.5$ A, $dI/dt \le 75$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C.
- d. 1.6 mm from case.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply



THERMAL RESISTANCE RATINGS						
PARAMETER SYMBOL TYP. MAX. UNIT						
Maximum Junction-to-Ambient	R _{thJA}	-	62			
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-	°C/W		
Maximum Junction-to-Case (Drain)	R _{thJC}	-	1.7			

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	0 V, I _D = 250 μA	500	=	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.61	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}	V	' _{GS} = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}		500 V, V _{GS} = 0 V V _{GS} = 0 V, T _J = 125 °C		-	25 250	μA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 \text{ V}$	$I_D = 2.7 \text{ Ab}$	_	_	1.5	Ω
Forward Transconductance	9 _{fs}		50 V, I _D = 2.7 A ^b	2.5	-	-	S
Dynamic	J13						
Input Capacitance	C _{iss}		V _{GS} = 0 V,	-	610	-	
Output Capacitance	C _{oss}	1	$V_{DS} = 25 \text{ V},$	-	160	_	pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0	0 MHz, see fig. 5	-	68	-	
Total Gate Charge	Qg			-	-	38	nC
Gate-Source Charge	Q_{gs}	V _{GS} = 10 V	$I_D = 3.1 \text{ A}, V_{DS} = 400 \text{ V},$	-	-	5.0	
Gate-Drain Charge	Q_{gd}		see fig. 6 and 13 ^b	-	-	22	
Turn-On Delay Time	t _{d(on)}		1	-	8.2	-	
Rise Time	t _r	$V_{DD} =$	250 V, I _D = 3.1 A	-	16	-	
Turn-Off Delay Time	t _{d(off)}	R_{q} = 12 Ω, R_{D} = 79 Ω, see fig. 10 ^b		-	42	-	ns
Fall Time	t _f	g,	.g ,	-	16	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	
Internal Source Inductance	L _S			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	s	•			L		l
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	4.5	A
Pulsed Diode Forward Current ^a	I _{SM}			1	-	18	
Body Diode Voltage	V_{SD}	T _J = 25 °C, I _S = 4.5 A, V _{GS} = 0 V ^b		-	-	1.6	V
Body Diode Reverse Recovery Time	t _{rr}	- T _J = 25 °C, I _F = 3.1 A, dI/dt = 100 A/μs ^b		-	320	640	ns
Body Diode Reverse Recovery Charge	Q_{rr}			-	1.0	2.0	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and				L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300~\mu s;$ duty cycle $\leq 2~\%.$



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

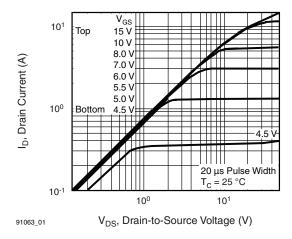


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

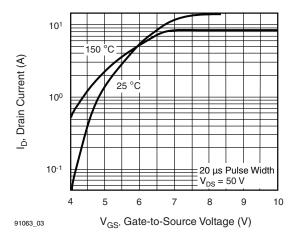


Fig. 3 - Typical Transfer Characteristics

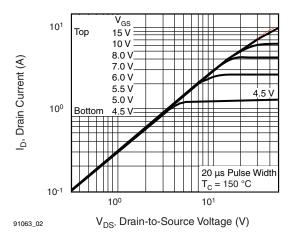


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

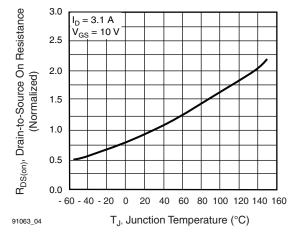


Fig. 4 - Normalized On-Resistance vs. Temperature



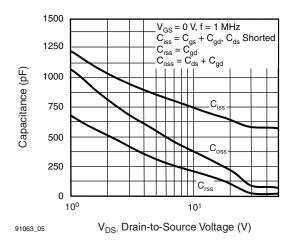


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

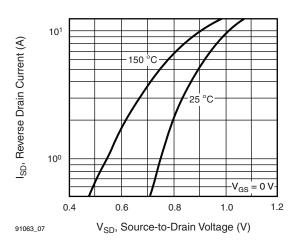


Fig. 7 - Typical Source-Drain Diode Forward Voltage

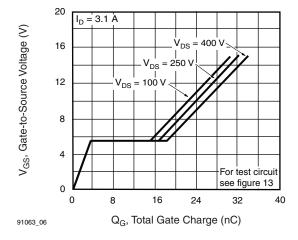


Fig. 6 - Typical Gate Charge vs. Drain-to-Source Voltage

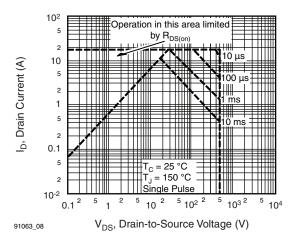


Fig. 8 - Maximum Safe Operating Area





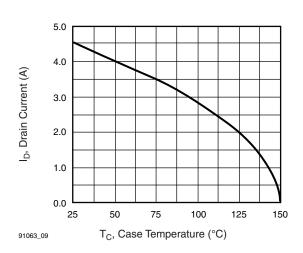


Fig. 9 - Maximum Drain Current vs. Case Temperature

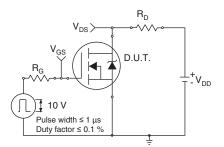


Fig. 10a - Switching Time Test Circuit

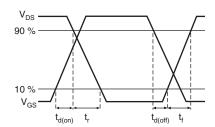


Fig. 10b - Switching Time Waveforms

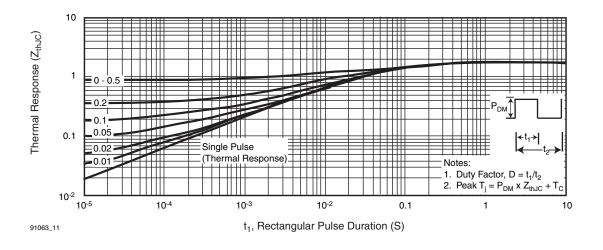


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



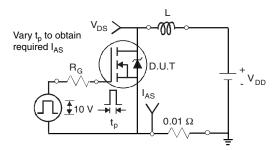


Fig. 12a - Unclamped Inductive Test Circuit

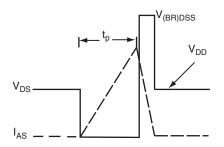


Fig. 12b - Unclamped Inductive Waveforms

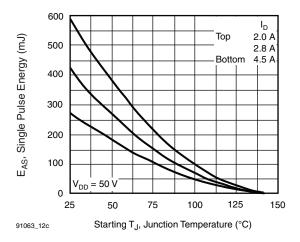


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

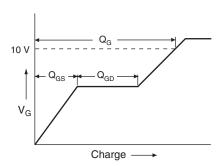


Fig. 13a - Basic Gate Charge Waveform

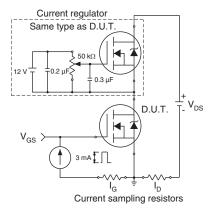
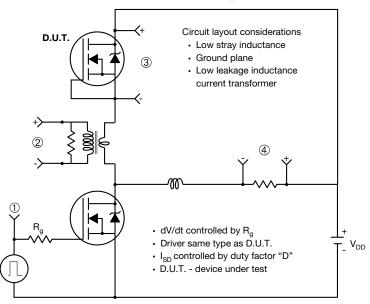


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



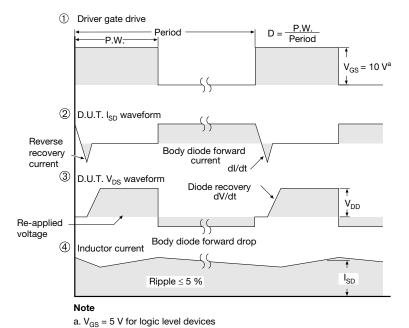
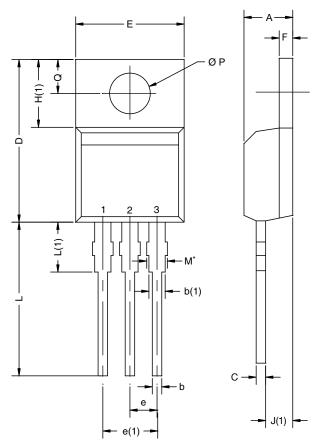


Fig. 14 - For N-Channel

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TO-220AB



		D2

	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	4.25	4.65	0.167	0.183	
b	0.69	1.01	0.027	0.040	
b(1)	1.20	1.73	0.047	0.068	
С	0.36	0.61	0.014	0.024	
D	14.85	15.49	0.585	0.610	
D2	12.19	12.70	0.480	0.500	
Е	10.04	10.51	0.395	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.09	6.48	0.240	0.255	
J(1)	2.41	2.92	0.095	0.115	
L	13.35	14.02	0.526	0.552	
L(1)	3.32	3.82	0.131	0.150	
ØΡ	3.54	3.94	0.139	0.155	
Q	2.60	3.00	0.102	0.118	
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471					

Note

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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Vishay

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Revision: 02-Oct-12 Document Number: 91000

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